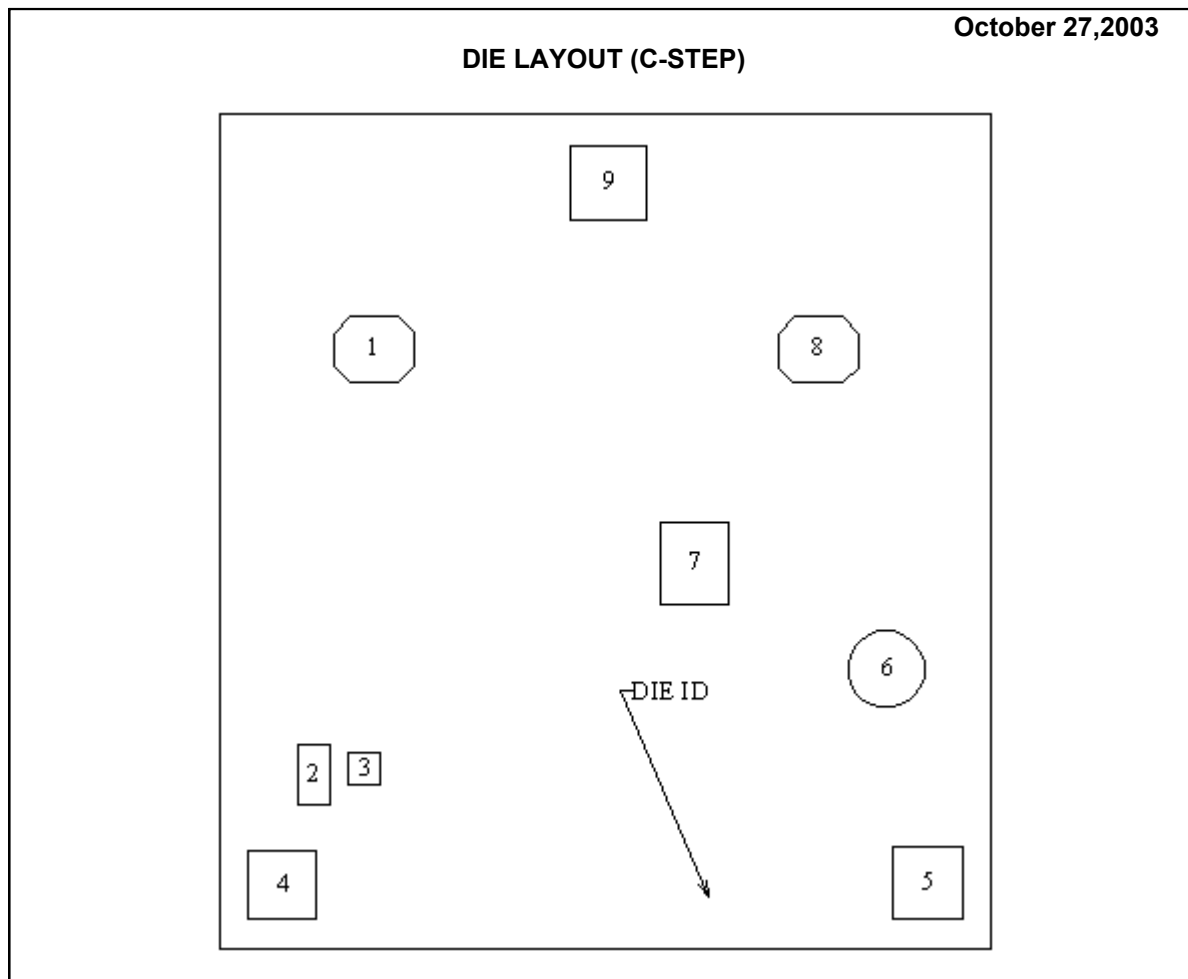


LM117HVKG MW8 MCD1700A
3-TERMINAL ADJUSTABLE REGULATOR



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	117C	Bond Pad Opening Size (min)	229μm x 188μm
Die Step	C	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	100 or 150mm	Back Side Metal	Gold
Die Size (Drawn)	2362μm x 2184μm 93.0mils x 86.0mils	Back Side Connection	OUTPUT
Thickness	254μm Nominal		
Min Pitch	146μm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (C -Step)

 (Referenced to die center, coordinates in μm) **NC** = No Connection, **N.U.** = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES		PAD SIZE		
		X	Y	X	Y	
OUTPUT	1	-655	516	229	x	188
NC	2	-827	-690	89	x	170
NC	3	-681	-673	91	x	91
OUTPUT	4	-914	-1001	193	x	198
ADJ	5	913	-997	196	x	206
NC	6	800	-391	208	x	208
INPUT	7	254	-91	193	x	234
OUTPUT	8	603	514	226	x	185
INPUT	9	10	987	213	x	211

LM117HVKG MW8 MCD1700A**3-TERMINAL ADJUSTABLE REGULATOR****Life Support Policy**

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